

Solid Tantalum Chip Capacitors, TANTAMOUNT®, Ultra-Low ESR, Conformal Coated, Maximum CV



PERFORMANCE CHARACTERISTICS

www.vishav.com/doc?40088

Operating Temperature: -55 °C to +125 °C (above 85 °C, voltage derating is required) **Capacitance Range:** 10 μF to 1500 μF

Capacitance Tolerance: ± 10 %, ± 20 % standard

Voltage Rating: 4 V_{DC} to 75 V_{DC}

FEATURES

- New case size offerings
- Terminations: 100 % tin (2) standard; tin/lead available

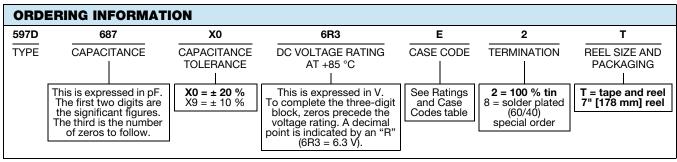


Extremely low ESR

- · Mounting: surface mount
- Ripple current up to 4.1 A
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and/or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information/tables in this datasheet for details.



Note

Preferred tolerance and reel sizes are in bold.
 We reserve the right to supply higher voltage ratings and tighter capacitance tolerance capacitors in the same case size.
 Low ESR solid tantalum chip capacitors allow delta ESR of 1.25 times the datasheet limits after mounting.

DIMENSION	DIMENSIONS in inches [millimeters]						
	† H	J nil an	ntalum wire or identifies lode (+) rminal		• W •		
CASE CODE	L (MAX.)	W	Н	Α	В	D (REF.)	J (MAX.)
V	0.299	0.173 ± 0.016	0.079	0.051 ± 0.012	0.181 ± 0.024	0.252	0.004
	[7.6]	[4.4 ± 0.4]	[2.0 max.]	[1.3 ± 0.3]	[4.6 ± 0.6]	[6.4]	[0.1]
D	0.299	0.173 ± 0.016	0.138	0.051 ± 0.012	0.181 ± 0.024	0.252	0.004
	[7.6]	[4.4 ± 0.4]	[3.5 max.]	[1.3 ± 0.3]	[4.6 ± 0.6]	[6.4]	[0.1]
Е	0.299	0.173 ± 0.016	0.157 ± 0.016	0.051 ± 0.012	0.181 ± 0.024	0.252	0.004
	[7.6]	[4.4 ± 0.4]	[4.0 ± 0.4]	[1.3 ± 0.3]	[4.6 ± 0.6]	[6.4]	[0.1]
R	0.299	0.238 ± 0.016	0.142 ± 0.016	0.051 ± 0.012	0.181 ± 0.024	0.244	0.004
	[7.6]	[6.0 ± 0.4]	[3.6 ± 0.4]	[1.3 ± 0.3]	[4.6 ± 0.6]	[6.2]	[0.1]
F	0.299	0.238 ± 0.016	0.185 ± 0.016	0.055 ± 0.016	0.181 ± 0.024	0.244	0.004
	[7.6]	[6.0 ± 0.4]	[4.7 ± 0.4]	[1.4 ± 0.4]	[4.6 ± 0.6]	[6.2]	[0.1]
Z	0.299 [7.6]	0.238 ± 0.016 $[6.0 \pm 0.4]$	0.236 ± 0.016 [6.0 ± 0.4]	0.055 ± 0.016 [1.4 ± 0.4]	0.181 ± 0.024 [4.6 ± 0.6]	0.244 [6.2]	0.004 [0.1]
М	0.315	0.260 + 0.016/- 0.024	0.142 ± 0.016	0.051 ± 0.012	0.197 ± 0.024	0.260	0.004
	[8.0]	[6.6 + 0.4/- 0.6]	[3.6 ± 0.4]	[1.3 ± 0.3]	[5.0 ± 0.6]	[6.6]	[0.1]
Н	0.315	0.260 + 0.016/- 0.024	0.205 ± 0.016	0.055 ± 0.016	0.197 ± 0.024	0.260	0.004
	[8.0]	[6.6 + 0.4/- 0.6]	[5.2 ± 0.4]	[1.4 ± 0.4]	[5.0 ± 0.6]	[6.6]	[0.1]

Note

Revision: 24-Jun-14

• The anode termination (D less B) will be a minimum of 0.012" [0.3 mm]



RATIN	GS AND	CASE C	DDES								
μF	4 V	6.3 V	10 V	16 V	20 V	25 V	35 V	40 V	50 V	63 V	75 V
10										D	R
15									E/R	R	
22									R	F	
33									F		
47							R		Z		
68						R	F				
100						F	F	Н			
150						F					
220				Е	R	М					
330		V	Е	F	Н						
470	V	Е	Е	Н							
680	Е	Е	R								
1000	E/R	R	F								
1500	R										
2200											

CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μA)	MAX. DF AT +25 °C 120 Hz (%)	MAX. ESR AT +25 °C 100 kHz (mΩ)	MAX. RIPPLE 100 kHz I _{RMS} (A)
		4 V _{DC} AT +85 °	C; 2.7 V _{DC} AT +125	5 °C		
470	V	597D477(1)004V(2)(3)	19	8	60	2.2
680	E	597D687(1)004E(2)(3)	27	6	25	2.9
1000	E	597D108(1)004E(2)(3)	40	8	20	3.3
1000	R	597D108(1)004R(2)(3)	40	8	18	3.7
1500	R	597D158(1)004R(2)(3)	60	8	24	2.9
		6.3 V _{DC} AT +85	°C; 4 V _{DC} AT +125	5 °C		
330	V	597D337(1)6R3V(2)(3)	21	8	56	2.0
470	E	597D477(1)6R3E(2)(3)	30	6	30	2.7
680	E	597D687(1)6R3E(2)(3)	43	6	25	2.9
1000	R	597D108(1)6R3R(2)(3)	63	8	31	2.8
		10 V _{DC} AT +85	°C; 7 V _{DC} AT +125	°C		
330	Е	597D337(1)010E(2)(3)	33	6	35	2.5
470	Е	597D477(1)010E(2)(3)	47	6	28	2.8
680	R	597D687(1)010R(2)(3)	68	6	28	3.0
1000	F	597D108(1)010F(2)(3)	100	20	120	1.4
		16 V _{DC} AT +85	°C; 10 V _{DC} AT +12	5 °C		
220	Е	597D227(1)016E(2)(3)	35	8	60	2.3
330	F	597D337(1)016F(2)(3)	53	10	100	1.6
470	Н	597D477(1)016H(2)(3)	75	14	100	1.4
		20 V _{DC} AT +85	°C; 13 V _{DC} AT +12	5 °C		
220	R	597D227(1)020R(2)(3)	44	8	80	1.8
330	Н	597D337(1)020H(2)(3)	66	10	100	1.6
		25 V _{DC} AT +85	°C; 17 V _{DC} AT +12	5 °C		
68	R	597D686(1)025R(2)(3)	17	6	100	1.6
100	F	597D107(1)025F(2)(3)	25	8	100	1.6

Note

- Part number definitions:
 - (1) Tolerance: for 10 % tolerance, specify "X9", for 20 % tolerance, change to "X0" (2) Termination: for 100 % tin specify "2", for solder plated 60/40 specify "8" (3) Packaging code: for 7" reels specify "T"

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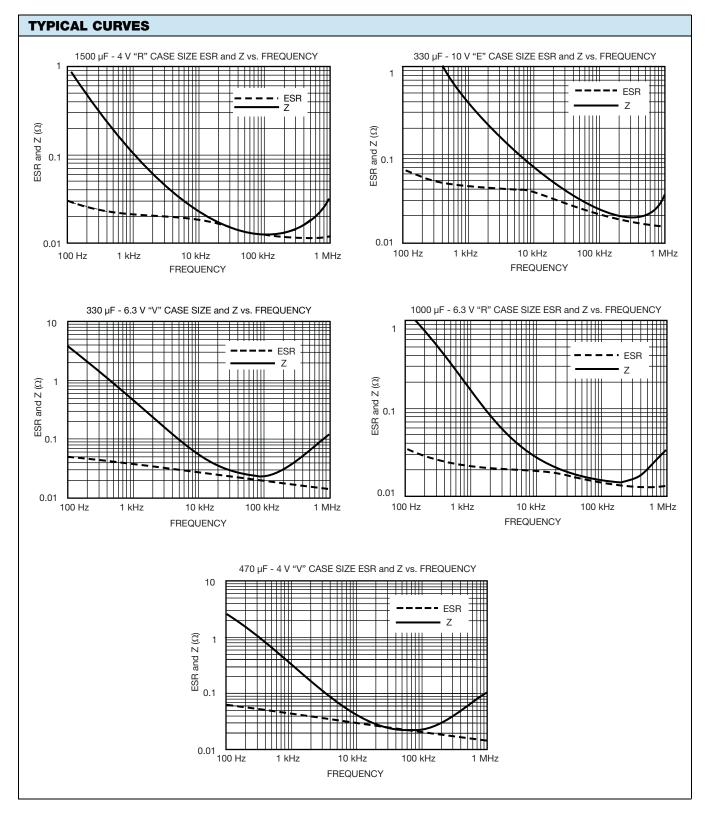
STANDARD	RATINGS					
CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μA)	MAX. DF AT +25 °C 120 Hz (%)	MAX. ESR AT +25 °C 100 kHz (mΩ)	MAX. RIPPLE 100 kHz I _{RMS} (A)
		25 V _{DC} AT +85 °	°C; 17 V _{DC} AT +12	5 °C		
150	F	597D157(1)025F(2)(3)	38	8	80	1.8
220	M	597D227(1)025M(2)(3)	55	8	100	1.6
	35 V _{DC} AT +85 °C; 23 V _{DC} AT +125 °C					
47	R	597D476(1)035R(2)(3)	17	6	100	1.6
68	F	597D686(1)035F(2)(3)	24	6	100	1.6
100	F	597D107X0035F(2)(3)	35	8	100	1.6
		40 V _{DC} AT +85 °	°C; 26 V _{DC} AT +12	5 °C		
100	Н	597D107X0040H(2)(3)	40	10	150	1.3
		50 V _{DC} AT +85 °	°C; 33 V _{DC} AT +12	5 °C		
15	E	597D156(1)050E(2)(3)	8	6	300	0.9
15	R	597D156(1)050R(2)(3)	8	6	250	1.0
22	R	597D226(1)050R(2)(3)	11	6	220	1.1
33	F	597D336(1)050F(2)(3)	17	6	150	1.3
47	Z	597D476(1)050Z(2)(3)	24	6	240	1.1
		63 V _{DC} AT +85 °	°C; 42 V _{DC} AT +12	5 °C		
10	D	597D106(1)063D(2)(3)	10	6	400	0.6
15	R	597D156(1)063R(2)(3)	10	6	400	0.8
22	F	597D226(1)063F(2)(3)	14	6	250	1.0
		75 V _{DC} AT +85 °	°C; 50 V _{DC} AT +12	5 °C		
10	R	597D106(1)075R(2)(3)	8	6	500	0.7

Note

- Part number definitions:
- (1) Tolerance: for 10 % tolerance, specify "X9", for 20 % tolerance, change to "X0" (2) Termination: for 100 % tin specify "2", for solder plated 60/40 specify "8" (3) Packaging code: for 7" reels specify "T"

ECOMMENDED VOLTAGE DERATING GUIDELINE	(for temperature below +85 °C)
TANDARD CONDITIONS. FOR EXAMPLE: OUTPUT FILTERS	0 " V "
Capacitor Voltage Rating	Operating Voltage
4.0	2.5
6.3	3.6
10	6.0
16	10
20	12
25	15
35	24
40	26
50	28
63	37.8
75	45
VERE CONDITIONS. FOR EXAMPLE: INPUT FILTERS	
Capacitor Voltage Rating	Operating Voltage
4.0	2.5
6.3	3.3
10	5.0
16	8.0
20	10
25	12
35	15
40	20
50	24
63	32
75	37







POWER DISSIPATION	
CASE CODE	MAXIMUM PERMISSIBLE POWER DISSIPATION AT +25 °C (W) IN FREE AIR
V	0.141
D	0.215
E	0.240
R, F, M	0.250
Z	0.265
Н	0.265

STANDARD PACKAGING QUANTITY				
CASE CODE	UNITS PER 7" REEL			
V	1000			
D	400			
E	500			
R	300			
F	250			
Z	250			
M	200			
Н	200			

PRODUCT INFORMATION				
Conformal Coated Guide				
Pad Dimensions	www.vishay.com/doc?40150			
Packaging Dimensions				
Moisture Sensitivity	www.vishay.com/doc?40135			
SELECTOR GUIDES				
Solid Tantalum Selector Guide	www.vishay.com/doc?49053			
FAQ				
Frequently Asked Questions	www.vishay.com/doc?40110			

Typical Performance Characteristics

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Typical Performance Characteristics Tantalum Capacitors

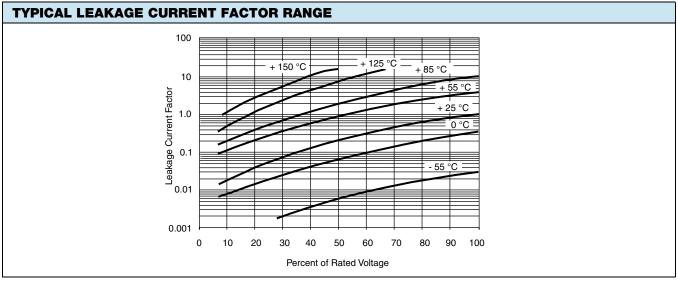
CAPACITOR ELECTRICAL PERFORMANCE CHARACTERISTICS						
ITEM	PERFORMANCE CHAR	ACTERISTICS				
Category temperature range	-55 °C to +85 °C (to +12	5 °C with voltage derating)				
Capacitance tolerance	± 20 %, ± 10 % (at 120 l	Hz) 2 V _{RMS} (max.) at +25 °C	using a capacitance bridge	e		
Dissipation factor	Limit per Standard Ratin	gs table. Tested via bridge	method, at 25 °C, 120 Hz			
ESR	Limit per Standard Ratin	gs table. Tested via bridge	method, at 25 °C, 100 kHz			
Leakage current	1 k Ω resistor in series with 0.5 μ A, whichever is great	th the capacitor under test,	itors for 5 min using a steal leakage current at 25 °C is current varies with tempera- tor.	not more than 0.01 CV or		
Capacitance change by temperature	+12 % max. (at +125 °C) +10 % max. (at +85 °C) -10 % max. (at -55 °C)					
Reverse voltage	Capacitors are capable of withstanding peak voltages in the reverse direction equal to: 10 % of the DC rating at +25 °C 5 % of the DC rating at +85 °C Vishay does not recommend intentional or repetitive application of reverse voltage					
Temperature derating	If capacitors are to be used at temperatures above +25 °C, the permissible RMS ripple current or voltage shall be calculated using the derating factors: 1.0 at +25 °C 0.9 at +85 °C 0.4 at +125 °C					
Operating temperature	+85	5 °C	+12	+125 °C		
	RATED VOLTAGE (V)	SURGE VOLTAGE (V)	RATED VOLTAGE (V)	SURGE VOLTAGE (V)		
	4	5.2	2.7	3.4		
	6.3	8	4	5		
	10	13	7	8		
	16	20	10	12		
	20	26	13	16		
	25	32	17	20		
	35	46	23	28		
	50	65	33	40		
	50 (1)	60	33	40		
	63	76	42	50		
	75 ⁽²⁾	75	50	50		

Notes

- All information presented in this document reflects typical performance characteristics.
- $^{(1)}\,$ Capacitance values 15 μF and higher.
- (2) For 293D and TR3 only.

Typical Performance Characteristics

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Notes

- At +25 °C, the leakage current shall not exceed the value listed in the Standard Ratings table.
- At +85 °C, the leakage current shall not exceed 10 times the value listed in the Standard Ratings table.
- At +125 °C, the leakage current shall not exceed 12 times the value listed in the Standard Ratings table.

CAPACITOR PE	CAPACITOR PERFORMANCE CHARACTERISTICS				
ITEM	PERFORMANCE CHARACTERISTICS				
Surge voltage	Post application of surge voltage (as specified in the table above) in series with a 33 Ω resistor at the rate of 30 s ON, 30 s OFF, for 1000 successive test cycles at 85 °C, capacitors meet the characteristics requirements listed below.				
	Capacitance change Dissipation factor Leakage current	Within ± 10 % of initial value Initial specified value or less Initial specified value or less			
Surge current	After subjecting parts in series with a 1 Ω resistor at the rate of 3 s CHARGE, 3 s DISCHARGE, and a cap bank of 100K μF for 3 successive test cycles at 25 °C, capacitors meet the characteristics requirements listed below. Capacitance change Within ± 10 % of initial value				
	Dissipation factor Leakage current	Initial specified value or less Initial specified value or less			
Life test at +85 °C	Capacitors meet the characteristic require	ements listed below. After 2000 h application of rated voltage at 85 °C.			
	Capacitance change Leakage current	Within \pm 10 % of initial value Shall not exceed 125 % of initial value			
Life test at +125 °C	Capacitors meet the characteristic requirements listed below. After 1000 h application 2/3 of rated voltage at 125 °C.				
	Capacitance change for parts with cap. ≤ 600 μF for parts with cap. > 600 μF Leakage current	Within \pm 10 % of initial value Within \pm 20 % of initial value Shall not exceed 125 % of initial value			

Typical Performance Characteristics

CAPACITOR ENVIR	CAPACITOR ENVIRONMENTAL CHARACTERISTICS				
ITEM	CONDITION	ENVIRONMENTAL CHARACTERISTICS			
Humidity tests	At 40 °C/90 % RH 1000 h, no voltage applied.	Capacitance change Cap. $\leq 600~\mu\text{F}$ Within $\pm 10~\%$ of initial value Within $\pm 20~\%$ of initial value Within $\pm 20~\%$ of initial value Not to exceed 150 % of initial value	lue		
Temperature cycles	At -55 °C/+125 °C, 30 min each, for 5 cycles.	Capacitance change Cap. $\leq 600 \ \mu F$ Within $\pm 10 \ \%$ of initial value or leakage current Within $\pm 20 \ \%$ of initial value or leakage current Unitial specified value or leakage capacitance change Within $\pm 20 \ \%$ of initial specified value or leakage current Unitial specified value or leakage capacitance change Within $\pm 10 \ \%$ of initial value or leakage capacitance change Within $\pm 10 \ \%$ of initial value or leakage capacitance change Within $\pm 10 \ \%$ of initial value or leakage capacitance change Within $\pm 10 \ \%$ of initial value or leakage capacitance change Within $\pm 10 \ \%$ of initial value or leakage capacitance change Within $\pm 10 \ \%$ of initial value or leakage capacitance change Within $\pm 10 \ \%$ of initial value or leakage capacitance change Within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ of initial value or leakage capacitance change within $\pm 10 \ \%$ or initial value or leakage capacitance change within $\pm 10 \ \%$ or initial value or leakage capacitance change within $\pm 10 \ \%$ or initial value or leakage capacitance change within $\pm 10 \ \%$ or initial value or leakage capacitance change within $\pm 10 \ \%$ or initial value or leakage capacitance change within $\pm 10 \ \%$ or initial value or leakage change within $\pm 10 \ \%$ or initial value or leakage change within $\pm 10 \ \%$ or initial value or leakage change within	alue ess		
Moisture resistance	MIL-STD-202, method 106 at rated voltage, 42 cycles.	Capacitance change Cap. ≤ 600 µF Cap. > 600 µF Dissipation factor Leakage current Within ± 10 % of initial value or leading to the company of the company of the capacitance change. Within ± 20 % of initial value or leading to the capacitance change. Within ± 10 % of initial value or leading to the capacitance change.	alue ess		
Thermal shock	Capacitors are subjected to 5 cycles of the following: -55 °C (+0 °C, -5 °C) for 30 min, then +25 °C (+10 °C, -5 °C) for 5 min, then +125 °C (+3 °C, -0 °C) for 30 min, then +25 °C (+10 °C, -5 °C) for 5 min	Capacitance change Cap. ≤ 600 μF Cap. > 600 μF Dissipation factor Leakage current Within ± 10 % of initial value or leading to the second se	lue ess		

MECHANICAL PERI	FORMANCE CHARACTERISTICS	
TEST CONDITION	CONDITION	POST TEST PERFORMANCE
Shear test	Apply a pressure load of 5 N for 10 s \pm 1 s horizontally to the center of capacitor side body.	Capacitance change Dissipation factor Leakage current Within ± 10 % of initial value Initial specified value or less Initial specified value or less
		There shall be no mechanical or visual damage to capacitors post-conditioning.
Substrate bend	With parts soldered onto substrate test board, apply force to the test board for a deflection of 3 mm, for a total of 3 bends at a rate of 1 mm/s.	Capacitance change Dissipation factor Leakage current Within ± 10 % of initial value Initial specified value or less Initial specified value or less
Vibration	MIL-STD-202, method 204, condition D, 10 Hz to 2000 Hz, 20 <i>g</i> peak	Capacitance change Dissipation factor Leakage current Within ± 10 % of initial value Initial specified value or less Initial specified value or less
		There shall be no mechanical or visual damage to capacitors post-conditioning.
Shock	MIL-STD-202, method 213B shock (specified pulse), condition I, 100 g peak	Capacitance change Dissipation factor Leakage current Within ± 10 % of initial value Initial specified value or less Initial specified value or less
		There shall be no mechanical or visual damage to capacitors post-conditioning.
Resistance to solder heat	Recommended reflow profiles temperatures and durations are located within the Capacitor Series Guides	Capacitance change Dissipation factor Leakage current Within ± 10 % of initial value Initial specified value or less Initial specified value or less
	Pb-free and lead-bearing series caps are backward and forward compatible	There shall be no mechanical or visual damage to capacitors post-conditioning.
Solderability	MIL-STD-2002, method 208, ANSI/J-STD-002, test B. Applies only to solder and tin plated terminations.	Capacitance change Dissipation factor Leakage current Within ± 10 % of initial value Initial specified value or less Initial specified value or less
	Does not apply to gold terminations.	There shall be no mechanical or visual damage to capacitors post-conditioning.
Resistance to solvents	MIL-STD-202, method 215	Capacitance change Dissipation factor Leakage current Within ± 10 % of initial value Initial specified value or less Initial specified value or less
		There shall be no mechanical or visual damage to capacitors post-conditioning.
Flammability	Encapsulent materials meet UL 94 V-0 with an oxygen index of 32 %.	

Guide for Conformal Coated Tantalum Capacitors

INTRODUCTION

Tantalum electrolytic capacitors are the preferred choice in applications where volumetric efficiency, stable electrical parameters, high reliability, and long service life are primary considerations. The stability and resistance to elevated temperatures of the tantalum/tantalum oxide/manganese dioxide system make solid tantalum capacitors an appropriate choice for today's surface mount assembly technology.

Vishay Sprague has been a pioneer and leader in this field, producing a large variety of tantalum capacitor types for consumer, industrial, automotive, military, and aerospace electronic applications.

Tantalum is not found in its pure state. Rather, it is commonly found in a number of oxide minerals, often in combination with Columbium ore. This combination is known as "tantalite" when its contents are more than one-half tantalum. Important sources of tantalite include Australia, Brazil, Canada, China, and several African countries. Synthetic tantalite concentrates produced from tin slags in Thailand, Malaysia, and Brazil are also a significant raw material for tantalum production.

Electronic applications, and particularly capacitors, consume the largest share of world tantalum production. Other important applications for tantalum include cutting tools (tantalum carbide), high temperature super alloys, chemical processing equipment, medical implants, and military ordnance.

Vishay Sprague is a major user of tantalum materials in the form of powder and wire for capacitor elements and rod and sheet for high temperature vacuum processing.

THE BASICS OF TANTALUM CAPACITORS

Most metals form crystalline oxides which are non-protecting, such as rust on iron or black oxide on copper. A few metals form dense, stable, tightly adhering, electrically insulating oxides. These are the so-called "valve" metals and include titanium, zirconium, niobium, tantalum, hafnium, and aluminum. Only a few of these permit the accurate control of oxide thickness by electrochemical means. Of these, the most valuable for the electronics industry are aluminum and tantalum.

Capacitors are basic to all kinds of electrical equipment, from radios and television sets to missile controls and automobile ignitions. Their function is to store an electrical charge for later use.

Capacitors consist of two conducting surfaces, usually metal plates, whose function is to conduct electricity. They are separated by an insulating material or dielectric. The dielectric used in all tantalum electrolytic capacitors is tantalum pentoxide.

Tantalum pentoxide compound possesses high-dielectric strength and a high-dielectric constant. As capacitors are being manufactured, a film of tantalum pentoxide is applied to their electrodes by means of an electrolytic process. The film is applied in various thicknesses and at various voltages and although transparent to begin with, it takes on different colors as light refracts through it. This coloring occurs on the tantalum electrodes of all types of tantalum capacitors.

Rating for rating, tantalum capacitors tend to have as much as three times better capacitance/volume efficiency than aluminum electrolytic capacitors. An approximation of the capacitance/volume efficiency of other types of capacitors may be inferred from the following table, which shows the dielectric constant ranges of the various materials used in each type. Note that tantalum pentoxide has a dielectric constant of 26, some three times greater than that of aluminum oxide. This, in addition to the fact that extremely thin films can be deposited during the electrolytic process mentioned earlier, makes the tantalum capacitor extremely efficient with respect to the number of microfarads available per unit volume. The capacitance of any capacitor is determined by the surface area of the two conducting plates, the distance between the plates, and the dielectric constant of the insulating material between the plates.

COMPARISON OF CAPACITOR DIELECTRIC CONSTANTS				
DIELECTRIC	e DIELECTRIC CONSTANT			
Air or vacuum	1.0			
Paper	2.0 to 6.0			
Plastic	2.1 to 6.0			
Mineral oil	2.2 to 2.3			
Silicone oil	2.7 to 2.8			
Quartz	3.8 to 4.4			
Glass	4.8 to 8.0			
Porcelain	5.1 to 5.9			
Mica	5.4 to 8.7			
Aluminum oxide	8.4			
Tantalum pentoxide	26			
Ceramic	12 to 400K			

In the tantalum electrolytic capacitor, the distance between the plates is very small since it is only the thickness of the tantalum pentoxide film. As the dielectric constant of the tantalum pentoxide is high, the capacitance of a tantalum capacitor is high if the area of the plates is large:

$$C = \frac{eA}{t}$$

where

C = Capacitance

e = Dielectric constant

A = Surface area of the dielectric

t = Thickness of the dielectric

Tantalum capacitors contain either liquid or solid electrolytes. In solid electrolyte capacitors, a dry material (manganese dioxide) forms the cathode plate. A tantalum lead is embedded in or welded to the pellet, which is in turn connected to a termination or lead wire. The drawings show the construction details of the surface mount types of tantalum capacitors shown in this catalog.



SOLID ELECTROLYTE TANTALUM CAPACITORS

Solid electrolyte capacitors contain manganese dioxide, which is formed on the tantalum pentoxide dielectric layer by impregnating the pellet with a solution of manganous nitrate. The pellet is then heated in an oven, and the manganous nitrate is converted to manganese dioxide.

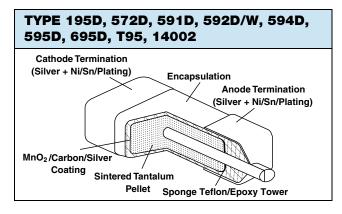
The pellet is next coated with graphite, followed by a layer of metallic silver, which provides a conductive surface between the pellet and the can in which it will be enclosed. After assembly, the capacitors are tested and inspected to assure long life and reliability. It offers excellent reliability and high stability for consumer and commercial electronics with the added feature of low cost.

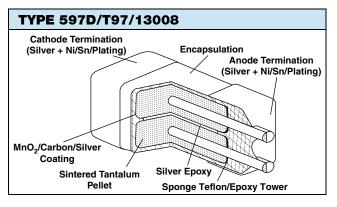
Surface mount designs of "Solid Tantalum" capacitors use lead frames or lead frameless designs as shown in the accompanying drawings.

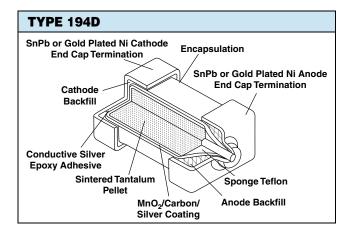
TANTALUM CAPACITORS FOR ALL DESIGN CONSIDERATIONS

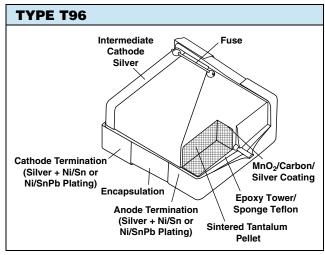
Solid electrolyte designs are the least expensive for a given rating and are used in many applications where their very small size for a given unit of capacitance is of importance. They will typically withstand up to about 10 % of the rated DC working voltage in a reverse direction. Also important are their good low temperature performance characteristics and freedom from corrosive electrolytes.

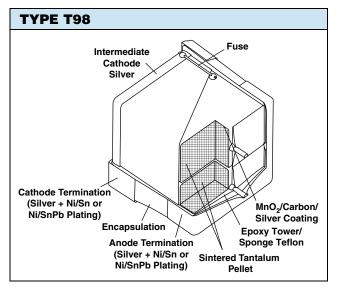
Vishay Sprague patented the original solid electrolyte capacitors and was the first to market them in 1956. Vishay Sprague has the broadest line of tantalum capacitors and has continued its position of leadership in this field. Data sheets covering the various types and styles of Vishay Sprague capacitors for consumer and entertainment electronics, industry, and military applications are available where detailed performance characteristics must be specified.













COMMERCIAL PRODUCTS

SOLID TANTALUM CAPACITORS - CONFORMAL COATED					
SERIES	592W	592D	591D	595D	594D
PRODUCT IMAGE					
TYPE		Surface mount	TANTAMOUNT® chip, cor	nformal coated	
FEATURES	Low profile, robust design for use in pulsed applications	Low profile, maximum CV	Low profile, low ESR, maximum CV	Maximum CV	Low ESR, maximum CV
TEMPERATURE RANGE	- 55 °C to + 125 °C (above 40 °C, voltage deratig is required)	- 55 °C to + 125 °C (above 85 °C, voltage derating is required)			
CAPACITANCE RANGE	330 μF to 2200 μF	1 μF to 2200 μF	1 μF to 1500 μF	0.1 μF to 1500 μF	1 μF to 1500 μF
VOLTAGE RANGE	6 V to 10 V	4 V to 50 V	4 V to 50 V	4 V to 50 V	4 V to 50 V
CAPACITANCE TOLERANCE	± 20 %	± 10 %, ± 20 %	± 10 %, ± 20 %	± 10 %, ± 20 %	± 10 %, ± 20 %
LEAKAGE CURRENT		0.01 CV or 0.5 μA, whichever is greater			
DISSIPATION FACTOR	14 % to 45 %	4 % to 50 %	4 % to 50 %	4 % to 20 %	4 % to 20 %
CASE CODES	C, M, X	S, A, B, C, D, R, M, X	A, B, C, D, R, M	T, S, A, B, C, D, G, M, R	B, C, D, R
TERMINATION	100 % matte tin	100 %	matte tin standard, tin/	lead and gold plated av	ailable

SOLID TANTAL	SOLID TANTALUM CAPACITORS - CONFORMAL COATED					
SERIES	597D	572D	695D	195D	194D	
PRODUCT IMAGE						
TYPE		TANTAN	NOUNT® chip, conformal	coated		
FEATURES	Ultra low ESR, maximum CV, multi-anode	Low profile, maximum CV	Pad compatible with 194D and CWR06	US and European case sizes	Industrial version of CWR06/CWR16	
TEMPERATURE RANGE	- 55 °C to + 125 °C (above 85 °C, voltage derating is required)					
CAPACITANCE RANGE	10 μF to 1500 μF	2.2 μF to 220 μF	0.1 μF to 270 μF	0.1 μF to 330 μF	0.1 μF to 330 μF	
VOLTAGE RANGE	4 V to 75 V	4 V to 35 V	4 V to 50 V	2 V to 50 V	4 V to 50 V	
CAPACITANCE TOLERANCE	± 10 %, ± 20 %					
LEAKAGE CURRENT	0.01 CV or 0.5 μA, whichever is greater					
DISSIPATION FACTOR	6 % to 20 %	6 % to 26 %	4 % to 8 %	4 % to 8 %	4 % to 10 %	
CASE CODES	V, D, E, R, F, Z, M, H	P, Q, S, A, B, T	A, B, D, E, F, G, H	C, S, V, X, Y, Z, R, A, B, D, E, F, G, H	A, B, C, D, E, F, G, H	
TERMINATION	100 % matte tin standard, tin/lead solder plated available	100 % matte tin standard, gold plated stin/lead and gold plated available and hot so			Gold plated standard; tin/lead solder plated and hot solder dipped available	

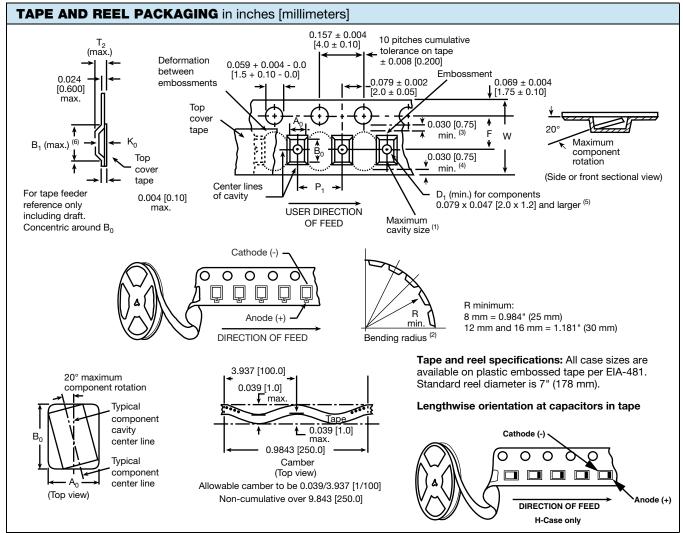


HIGH RELIABILITY PRODUCTS

SOLID TANTALUM CAPACITORS - CONFORMAL COATED						
SERIES	CWR06	CWR16	CWR26	13008	14002	
PRODUCT IMAGE						
TYPE		TANTAM	OUNT $^{ ext{@}}$ chip, conforma	l coated		
FEATURES	MIL-PRF-55365/4 qualified	DI A approved				
TEMPERATURE RANGE	- 55 °C to + 125 °C (above 85 °C, voltage derating is required)					
CAPACITANCE RANGE	0.10 μF to 100 μF	0.33 μF to 330 μF	10 μF to 100 μF	10 μF to 1500 μF	4.7 μF to 680 μF	
VOLTAGE RANGE	4 V to 50 V	4 V to 35 V	15 V to 35 V	4 V to 63 V	4 V to 50 V	
CAPACITANCE TOLERANCE	± 5 %, ± 10 %, ± 20 %	± 5 %, ± 10 %, ± 20 %	± 5 %, ± 10 %, ± 20 %	± 10 %, ± 20 %	± 10 %, ± 20 %	
LEAKAGE CURRENT	0.01 CV or 1.0 μA, whichever is greater 0.01 CV or 0.5 μA, whichever is greater					
DISSIPATION FACTOR	6 % to 10 %	6 % to 10 %	6 % to 12 %	6 % to 20 %	6 % to 14 %	
CASE CODES	A, B, C, D, E, F, G, H	A, B, C, D, E, F, G, H	F, G, H	V, E, F, R, Z, D, M, H, N	B, C, D, R	
TERMINATION	Gold plate	ed; tin/lead; tin/lead so	older fused	Tin/	lead	

SOLID TANTALUM CA	SOLID TANTALUM CAPACITORS - CONFORMAL COATED					
SERIES	T95	T96	Т97	T98		
PRODUCT IMAGE						
TYPE		TANTAMOUNT® chip, Hi-Re	I COTS, conformal coated			
FEATURES	High reliability	High reliability, built in fuse	High reliability, ultra low ESR, multi-anode	High reliability, ultra low ESR, built in fuse, multi-anode		
TEMPERATURE RANGE	- 55	- 55 °C to + 125 °C (above 85 °C, voltage derating is required)				
CAPACITANCE RANGE	0.15 μF to 680 μF	10 μF to 680 μF	10 μF to 1500 μF	10 μF to 1500 μF		
VOLTAGE RANGE	4 V to 50 V	4 V to 50 V	4 V to 75 V	4 V to 75 V		
CAPACITANCE TOLERANCE	± 10 %, ± 20 %	± 10 %, ± 20 %	± 10 %, ± 20 %	± 10 %, ± 20 %		
LEAKAGE CURRENT	0.01 CV or 0.5 μA, whichever is greater					
DISSIPATION FACTOR	4 % to 14 %	6 % to 14 %	6 % to 20 %	6 % to 10 %		
CASE CODES	A, B, C, D, R, S, V, X, Y, Z	R	V, E, F, R, Z, D, M, H, N	V, E, F, R, Z, M, H		
TERMINATION		100 % matte	e tin, tin/lead			

Vishay Sprague



Notes

- · Metric dimensions will govern. Dimensions in inches are rounded and for reference only.
- (1) A₀, B₀, K₀, are determined by the maximum dimensions to the ends of the terminals extending from the component body and/or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A₀, B₀, K₀) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°.
- (2) Tape with components shall pass around radius "R" without damage. The minimum trailer length may require additional length to provide "R" minimum for 12 mm embossed tape for reels with hub diameters approaching N minimum.
- (3) This dimension is the flat area from the edge of the sprocket hole to either outward deformation of the carrier tape between the embossed cavities or to the edge of the cavity whichever is less.
- (4) This dimension is the flat area from the edge of the carrier tape opposite the sprocket holes to either the outward deformation of the carrier tape between the embossed cavity or to the edge of the cavity whichever is less.
- (5) The embossed hole location shall be measured from the sprocket hole controlling the location of the embossement. Dimensions of embossement location shall be applied independent of each other.
- (6) B₁ dimension is a reference dimension tape feeder clearance only.





CARRIER TAPE DIMENSIONS in inches [millimeters]						
TAPE WIDTH	W	D_0	P ₂	F	E ₁	E _{2 min.}
8 mm	0.315 + 0.012/- 0.004 [8.0 + 0.3/- 0.1]		0.078 ± 0.0019	0.14 ± 0.0019 [3.5 ± 0.05]		0.246 [6.25]
12 mm	0.479 + 0.012/- 0.004 [12.0 + 0.3/- 0.1]	0.059 + 0.004/- 0	0.216 ± 0.0019 [5.5 ± 0.05]	0.324 ± 0.004	0.403 [10.25]	
16 mm	0.635 + 0.012/- 0.004 [16.0 + 0.3/- 0.1]	[1.5 + 0.1/- 0]	0.078 ± 0.004	0.295 ± 0.004 [7.5 ± 0.1]	[1.75 ± 0.1]	0.570 [14.25]
24 mm	0.945 ± 0.012 [24.0 ± 0.3]		$[2.0 \pm 0.1]$	0.453 ± 0.004 [11.5 ± 0.1]		0.876 [22.25]

CARRIER TAPE DIMENSIONS in inches [millimeters]					
TYPE	CASE CODE	TAPE WIDTH W IN mm	P ₁	K _{0 max.}	B _{1 max} .
	A	8	0.157 ± 0.004	0.058 [1.47]	0.149 [3.78]
	В	12	[4.0 ± 0.10]	0.088 [2.23]	0.166 [4.21]
	С	12		0.088 [2.23]	0.290 [7.36]
	D	12	0.315 ± 0.004	0.088 [2.23]	0.300 [7.62]
592D 592W	М	16	[8.0 ± 0.10]	0.091 [2.30]	0.311 [7.90]
591D	R	12		0.088 [2.23]	0.296 [7.52]
	S	8	0.157 ± 0.004	0.058 [1.47]	0.139 [3.53]
	Т	12	[4.0 ± 0.10]	0.088 [2.23]	0.166 [4.21]
	Х	24	0.472 ± 0.004 [12.0 ± 0.10]	0.011 [2.72]	0.594 [15.1]
	A	8	0.157 ± 0.004	0.063 [1.60]	0.152 [3.86]
	В	12	$[4.0 \pm 0.10]$	0.088 [2.23]	0.166 [4.21]
	С	12		0.118 [2.97]	0.290 [7.36]
	D	D 12 0.315 ±	0.315 ± 0.004	0.119 [3.02]	0.296 [7.52]
	G	12	[8.0 ± 0.10]	0.111 [2.83]	0.234 [5.95]
595D	Н	12		0.098 [2.50]	0.232 [5.90]
594D	М	12	0.157 ± 0.004 [4.0 ± 0.10]	0.085 [2.15]	0.152 [3.85]
	R	12	0.315 ± 0.004 [8.0 ± 0.10]	0.148 [3.78]	0.296 [7.52]
	S	8	0.157 ± 0.004	0.058 [1.47]	0.149 [3.78]
	Т	8	[4.0 ± 0.10]	0.054 [1.37]	0.093 [2.36]
	А	8		0.058 [1.47]	0.139 [3.53]
	В	12	0.157 ± 0.004	0.059 [1.50]	0.189 [4.80]
	D	12	$[4.0 \pm 0.10]$	0.063 [1.62]	0.191 [4.85]
	E 12		0.074 [1.88]	0.239 [6.07]	
695D	F	12	0.315 ± 0.004 [8.0 ± 0.10]	0.075 [1.93]	0.259 [6.58]
	G	12	0.157 ± 0.004 [4.0 ± 0.10]	0.109 [2.77]	0.301 [7.65]
	Н	16	0.315 ± 0.004 [8.0 ± 0.10]	0.124 [3.15]	0.31 [7.87]



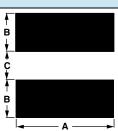
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		TAPE WIDTH			
TYPE	CASE CODE	W	P ₁	K _{0 max.}	B _{1 max} .
		IN mm			
	A	8		0.058 [1.47]	0.139 [3.53]
	В	12	0.157 ± 0.004	0.059 [1.50]	0.189 [4.80]
	С	8	$[4.0 \pm 0.10]$	0.054 [1.37]	0.093 [2.36]
	D	12	[]	0.067 [1.70]	0.179 [4.55]
	E	12		0.074 [1.88]	0.239 [6.07]
	F	12	0.315 ± 0.004 [8.0 ± 0.10]	0.076 [1.93]	0.259 [6.58]
	G	12	0.157 ± 0.004 [4.0 ± 0.10]	0.109 [2.77]	0.301 [7.65]
195D	H ⁽¹⁾	12	0.472 ± 0.004 [12.0 ± 0.1]	0.122 [3.11]	0.163 [4.14]
	R	12	0.315 ± 0.004 [8.0 ± 0.10]	0.149 [3.78]	0.296 [7.52]
	S	8	[0.0 ± 0.10]	0.058 [1.47]	0.149 [3.78]
	V	8	1	0.060 [1.52]	0.150 [3.80]
	X	12	0.157 ± 0.004	0.069 [1.75]	0.296 [7.52]
	Ŷ	12	$[4.0 \pm 0.10]$	0.089 [2.26]	0.296 [7.52]
	Z	12	1	0.114 [2.89]	0.288 [7.31]
	A	8		0.058 [1.47]	0.288 [7.31]
	В	12	1	0.038 [1.47]	0.149 [3.78]
	Р	8	1	0.047 [2.20]	0.100 [4.21]
72D	P	8	0.157 ± 0.004	0.043 [1.10]	0.102 [2.00]
יובט	Q	8	$[4.0 \pm 0.10]$	0.052 [1.32]	0.140 [3.55]
	S	8	1	0.054 [1.37]	0.140 [3.33]
	T	12	-	0.038 [1.47]	0.164 [4.16]
	A	8		0.061 [1.55]	0.139 [3.53]
			4		
	В	12	0.157 ± 0.004 [4.0 ± 0.10]	0.073 [1.85]	0.189 [4.80]
94D	С	12		0.069 [1.75]	0.244 [6.20]
WR06	D	12		0.068 [1.72]	0.191 [4.85]
CWR16 CWR26	E	12	ļ	0.074 [1.88]	0.239 [6.07]
7V1120	F	12	0.315 ± 0.004	0.091 [2.31]	0.262 [6.65]
	G	16	$[8.0 \pm 0.10]$	0.134 [3.40]	0.289 [7.34]
	H	16		0.129 [3.28]	0.319 [8.10]
	D	16	0.317 ± 0.004	0.150 [3.80]	0.313 [7.95]
	E	16	$[8.0 \pm 0.10]$	0.173 [4.40]	0.343 [8.70]
	F	16	4	0.205 [5.20]	0.309 [7.85]
	H	16	0.476 ± 0.004	0.224 [5.70]	0.313 [7.95]
97D	M	16	$[12.0 \pm 0.1]$	0.193 [4.90]	0.339 [8.60]
97 3008	N	16	1 1	0.283 [7.20]	0.323 [8.20]
0000	R	16		0.159 [4.05]	0.313 [7.95]
	V	12	0.317 ± 0.004 [8.0 ± 0.10]	0.088 [2.23]	0.300 [7.62]
	Z	16	0.476 ± 0.004 [12.0 ± 0.1]	0.239 [6.06]	0.311 [7.90]
	Α	8	0.157 ± 0.004	0.063 [1.60]	0.152 [3.86]
	В	12	$- [4.0 \pm 0.10]$	0.088 [2.23]	0.166 [4.21]
	С	12		0.117 [2.97]	0.290 [7.36]
	D	12	0.317 ± 0.004	0.119 [3.02]	0.296 [7.52]
95	R	12	$[8.0 \pm 0.10]$	0.149 [3.78]	0.296 [7.52]
00	S	8	_	0.058 [1.47]	0.149 [3.78]
	V	8	0.157 ± 0.004	0.060 [1.52]	0.150 [3.80]
	X	12	$- [4.0 \pm 0.10]$	0.069 [1.75]	0.296 [7.52]
	Y	12	[2 0. 10]	0.089 [2.26]	0.296 [7.52]
	Z	12		0.114 [2.89]	0.288 [7.31]
	В	12	0.157 ± 0.004	0.088 [2.23]	0.166 [4.21]
4000	С	12	$[4.0 \pm 0.10]$	0.117 [2.97]	0.290 [7.36]
4002	D	12	0.317 ± 0.004	0.119 [3.02]	0.296 [7.52]
	R	12	$[8.0 \pm 0.10]$	0.149 [3.78]	0.296 [7.52]
Г96	R	16	0.476 ± 0.004 [12.0 ± 0.1]	0.159 [4.05]	0.313 [7.95]
	F	16		0.239 [6.06]	0.311 [7.90]
98	M	16	0.476 ± 0.004	0.193 [4.90]	0.339 [8.60]
	Z	16	$[12.0 \pm 0.1]$	0.193 [4.90]	0.307 [7.80]

Note

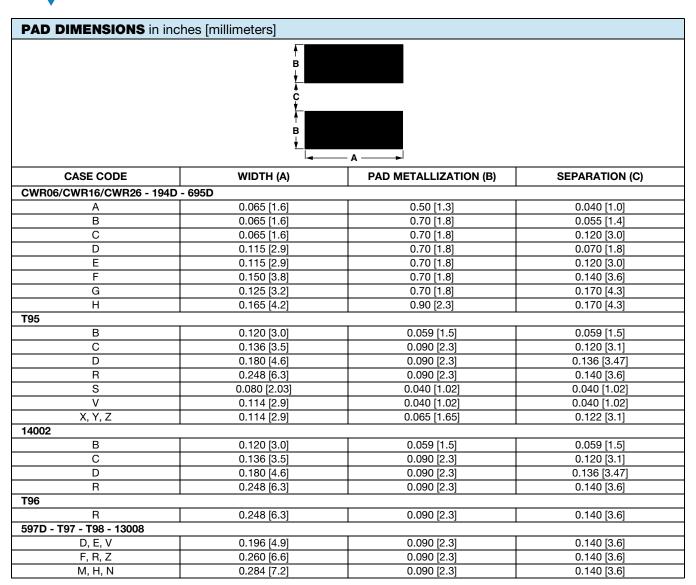
 $^{(1)}$ H case only, packaging code T: Lengthwise orientation at capacitors in tape.

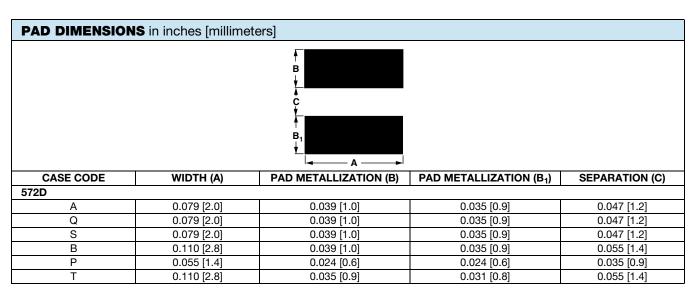
PAD DIMENSIONS in inches [millimeters]

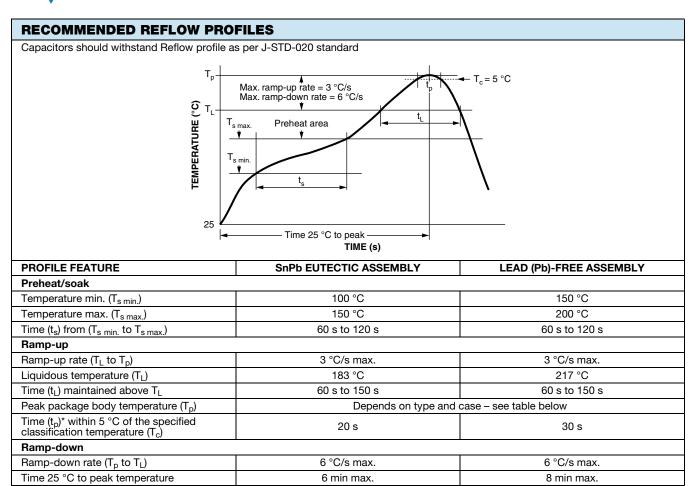


	A				
CASE CODE	WIDTH (A)	PAD METALLIZATION (B)	SEPARATION (C)		
592D/W - 591D					
Α	0.075 [1.9]	0.050 [1.3]	0.050 [1.3]		
В	0.118 [3.0]	0.059 [1.5]	0.059 [1.5]		
С	0.136 [3.5]	0.090 [2.3]	0.122 [3.1]		
D	0.180 [4.6]	0.090 [2.3]	0.134 [3.4]		
N4	0.056 [6.5]	Anode pad: 0.095 [2.4]	0.100 [0.5]		
M	0.256 [6.5]	Cathode pad: 0.067 [1.7]	0.138 [3.5]		
ר	0.040 [6.4]	Anode pad: 0.095 [2.4]	0.110 [0.0]		
R	0.240 [6.1]	Cathode pad: 0.067 [1.7]	0.118 [3.0]		
S	0.067 [1.7]	0.032 [0.8]	0.043 [1.1]		
Х	0.310 [7.9]	0.120 [3.0]	0.360 [9.2]		
595D - 594D		<u> </u>			
Т	0.059 [1.5]	0.028 [0.7]	0.024 [0.6]		
S	0.067 [1.7]	0.032 [0.8]	0.043 [1.1]		
A	0.083 [2.1]	0.050 [1.3]	0.050 [1.3]		
В	0.118 [3.0]	0.059 [1.5]	0.059 [1.5]		
С	0.136 [3.5]	0.090 [2.3]	0.122 [3.1]		
D	0.180 [4.6]	0.090 [2.3]	0.134 [3.4]		
G	0.156 [4.05]	0.090 [2.3]	0.082 [2.1]		
М	0.110 [2.8]	0.087 [2.2]	0.134 [3.4]		
R	0.248 [6.3]	0.090 [2.3]	0.140 [3.6]		
195D					
А	0.067 [1.7]	0.043 [1.1]	0.028 [0.7]		
В	0.063 [1.6]	0.047 [1.2]	0.047 [1.2]		
С	0.059 [1.5]	0.031 [0.8]	0.024 [0.6]		
D	0.090 [2.3]	0.055 [1.4]	0.047 [1.2]		
Е	0.090 [2.3]	0.055 [1.4]	0.079 [2.0]		
F	0.140 [3.6]	0.063 [1.6]	0.087 [2.2]		
G	0.110 [2.8]	0.059 [1.5]	0.126 [3.2]		
Н	0.154 [3.9]	0.063 [1.6]	0.140 [3.6]		
N	0.244 [6.2]	0.079 [2.0]	0.118 [3.0]		
R	0.248 [6.3]	0.090 [2.3]	0.140 [3.6]		
S	0.079 [2.0]	0.039 [1.0]	0.039 [1.0]		
V	0.114 [2.9]	0.039 [1.0]	0.039 [1.0]		
Х	0.118 [3.0]	0.067 [1.7]	0.122 [3.1]		
Υ	0.118 [3.0]	0.067 [1.7]	0.122 [3.1]		
Z	0.118 [3.0]	0.067 [1.7]	0.122 [3.1]		

Revision: 30-Jun-14 8 Document Number: 40150







TYPE/CASE CODE	PEAK PACKAGE BODY TEMPERATURE (Tp)			
TPE/CASE CODE	SnPb EUTECTIC PROCESS	LEAD (Pb)-FREE PROCESS		
591D/592D - all cases, except X25H, M and R cases	235 °C	260 °C		
591D/592D - X25H, M and R cases	220 °C	250 °C		
594D/595D - all cases except C, D, and R	235 °C	260 °C		
594D/595D - C, D, and R case	220 °C	250 °C		
572D all cases	n/a	260 °C		
T95 B, S, V, X, Y cases	235 °C	260 °C		
T95 B, S, V, X, Y cases	235 °C	260 °C		
T95 B, S, V, X, Y cases	235 °C	260 °C		
T95 C, D, R, and Z cases	220 °C	250 °C		
14002 B case	235 °C	n/a		
14002 C, D, and R cases	220 °C	n/a		
T96 R case	220 °C	250 °C		
195D all cases, except G, H, R, and Z	235 °C	260 °C		
195D G, H, R, and Z cases	220 °C	250 °C		
695D all cases, except G and H cases	235 °C	260 °C		
695D G, H cases	220 °C	250 °C		
597D, T97, T98 all cases, except V case	220 °C	250 °C		
597D, T97, T98 V case	230 °C	260 °C		
194D all cases, except H and G cases	235 °C	260 °C		
194D H and G cases	220 °C	250 °C		

GUIDE TO APPLICATION

 AC Ripple Current: The maximum allowable ripple current shall be determined from the formula:

$$I_{RMS} = \sqrt{\frac{P}{R_{ESR}}}$$

where,

P = Power dissipation in W at + 25 °C as given in the tables in the product datasheets (Power Dissipation).

R_{ESR} = The capacitor equivalent series resistance at the specified frequency

2. **AC Ripple Voltage:** The maximum allowable ripple voltage shall be determined from the formula:

$$V_{RMS} = I_{RMS} \times Z$$

or, from the formula:

$$V_{RMS} = Z \sqrt{\frac{P}{R_{ESR}}}$$

where,

P = Power dissipation in W at + 25 °C as given in the tables in the product datasheets (Power Dissipation).

R_{ESR} = The capacitor equivalent series resistance at the specified frequency

Z = The capacitor impedance at the specified frequency

- 2.1 The sum of the peak AC voltage plus the applied DC voltage shall not exceed the DC voltage rating of the capacitor.
- 2.2 The sum of the negative peak AC voltage plus the applied DC voltage shall not allow a voltage reversal exceeding 10 % of the DC working voltage at + 25 °C.
- 3. **Reverse Voltage:** Solid tantalum capacitors are not intended for use with reverse voltage applied. However, they have been shown to be capable of withstanding momentary reverse voltage peaks of up to 10 % of the DC rating at 25 °C and 5 % of the DC rating at + 85 °C.
- 4. **Temperature Derating:** If these capacitors are to be operated at temperatures above + 25 °C, the permissible RMS ripple current or voltage shall be calculated using the derating factors as shown:

TEMPERATURE	DERATING FACTOR
+ 25 °C	1.0
+ 85 °C	0.9
+ 125 °C	0.4

- 5. **Power Dissipation:** Power dissipation will be affected by the heat sinking capability of the mounting surface. Non-sinusoidal ripple current may produce heating effects which differ from those shown. It is important that the equivalent I_{RMS} value be established when calculating permissible operating levels. (Power dissipation calculated using derating factor (see paragraph 4)).
- 6. Attachment:
- 6.1 **Soldering:** Capacitors can be attached by conventional soldering techniques, convection, infrared reflow, wave soldering and hot plate methods. The soldering profile chart shows typical recommended time/temperature conditions for soldering. Preheating is recommended to reduce thermal stress. The recommended maximum preheat rate is 2 °C/s. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor.
- Recommended Mounting Pad Geometries: The nib must have sufficient clearance to avoid electrical contact with other components. The width dimension indicated is the same as the maximum width of the capacitor. This is to minimize lateral movement.
- 8. Cleaning (Flux Removal) After Soldering:

 TANTAMOUNT® capacitors are compatible with all commonly used solvents such as TES, TMS, Prelete, Chlorethane, Terpene and aqueous cleaning media. However, CFC/ODS products are not used in the production of these devices and are not recommended. Solvents containing methylene chloride or other epoxy solvents should be avoided since these will attack the epoxy encapsulation material.



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Vishay

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